

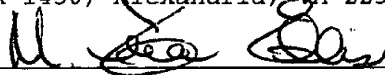


AF/2826

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on December 8, 2003.


Signature

Appl No. : 09/383,150
Applicant : Rong-Fuh Shyu
Filed : August 25, 1999
Title : LEAD FRAME FOR A SEMICONDUCTOR CHIP PACKAGE,
SEMICONDUCTOR CHIP PACKAGE INCORPORATING MULTIPLE
INTEGRATED CIRCUIT CHIPS, AND METHOD OF FABRICATING
A SEMICONDUCTOR CHIP...
TC/A.U. : 2826
Examiner : Fetsum Abraham
Docket No. : 35761/DBP/S295
Customer No. : 23363

LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Post Office Box 7068
Pasadena, CA 91109-7068
December 6, 2003

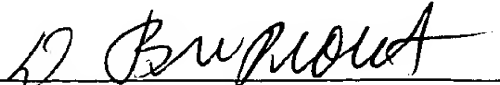
Commissioner:

The Final Rejection dated November 28, 2003 regarding the above-identified application applies only to claims 1-6, which were canceled in response to the June 23, 2003 official Office action. Therefore, the Office action does not address the claims now in this case.

Accordingly, it is requested that the November 28, 2003 Final Rejection be withdrawn and that a new Office action be issued properly addressing claims 9-12, the only claims now in this application.

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By 
D. Bruce Prout
Reg. No. 20,958
626/795-9900

DBP/mas
MAS PAS540059.1--12/6/03 5:47 PM